502171780 12/20/2012

PATENT ASSIGNMENT

Electronic Version v1.1 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Chih-Yang CHANG	12/14/2012
Wen-Ting CHU	12/14/2012
Kuo-Chi TU	12/14/2012
Yu-Wen LIAO	12/17/2012
Hsia-Wei CHEN	12/14/2012
Chin-Chieh YANG	12/14/2012

RECEIVING PARTY DATA

Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.
Street Address:	No. 8, Li-Hsin Rd. VI, Hsinchu Science Park
City:	Hsinchu
State/Country:	TAIWAN
Postal Code:	300

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	13722345

CORRESPONDENCE DATA

Fax Number: 7035185499

Correspondence will be sent via US Mail when the fax attempt is unsuccessful.

 Phone:
 7036841111

 Email:
 tsmc@ipfirm.com

Correspondent Name: Lowe Hauptman Ham & Berner, LLP (TSMC)

Address Line 1: 1700 Diagonal Road, Suite 300 Address Line 4: Alexandria, VIRGINIA 22314

ATTORNEY DOCKET NUMBER:	T5057-842	
NAME OF SUBMITTER:	Randy A. Noranbrock	

Total Attachments: 1

source=EfiledAssgn#page1.tif

PATENT REEL: 029512 FRAME: 0015 OF \$40.00 13/22345

ASSIGNMENT

In consideration of the premises and other g	good and valuable consideration	in hand paid	, the receipt and	d sufficiency of
which is hereby acknowledged, the undersigned,		•	•	

1) Chih-Yang CHANG

4) Yu-Wen LIAO

2) Wen-Ting CHU

5) Hsia-Wei CHEN

3) Kuo-Chi TU

6) Chin-Chieh YANG

who has made a certain new and useful invention, hereby sells, assigns and transfers unto TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD., having a place of business at No. 8, Li-Hsin Rd. VI, Hsinchu Science Park, Hsinchu 300, Taiwan R.O.C.

its successors and assigns (hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100 in the invention entitled

RESISTIVE RANDOM ACCESS MEMORY (RRAM) STRUCTURE AND METHOD OF

MAKING THE RRAM STRUCTURE

(a)	for which an application for United States Letters Patent was filed on 2	2012-12-20	and identified	Ъv
	United States Patent Application No. <u>13/722,345</u>	; or		-,

(b) for which an application for United States Letters Patent was executed on _____

and the undersigned hereby authorizes and requests the United States Commissioner of Patents and Trademarks to issue any and all United States Letters Patent which may be granted therefore and any and all extensions, divisions, reissues, continuations, or continuations-in-part thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agrees that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agrees to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE's full protection and title in and to the invention hereby transferred.

SIGNED on the date indicated aside my signature:

1) V Chih - Jang Chung Name: Chih-Yang CHANG	V Dec. 14 / 2012 Date:
2) V Mn - Trng Chu	V Dec. 14/2012
Name: Wen-Ting CHU 3) V Kw-Chi Tu	Date: V Dec. 14/2/2
Name: Kuo-Chi TU	Date:
4) V Yu- Wen Lino Name: Yu-Wen LIAO	<u>√ √ec, /7 / 2512</u> Date:
5) V HSia-Wei Chen Name: Hsia-Wei CHEN	V 0ec.14/2012 Date:
6) V Chin-Chieh Young	V Dec. 14/2012
Name: Chin-Chieh YANG	Date:

PATENT REEL: 029512 FRAME: 0016

RECORDED: 12/20/2012